

2SK2725

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1023-0400

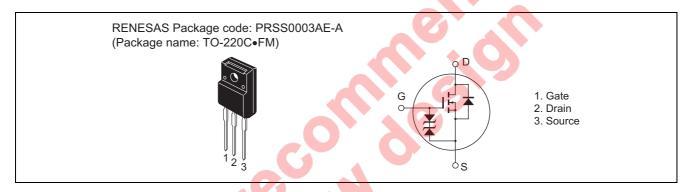
(Previous: ADE-208-452B)

Rev.4.00 Sep 07, 2005

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Avalanche ratings

Outline



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Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	500	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	5	А
Drain peak current	I _{D(pulse)} *1	20	Α
Body to drain diode reverse drain current	I _{DR}	5	Α
Avalanche current	I _{AP} *3	5	Α
Avalanche energy	E _{AR} *3	1.38	mJ
Channel dissipation	Pch*2	30	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at $Tc = 25^{\circ}C$

3. Value at Tch = 25°C, Rg \geq 50 Ω

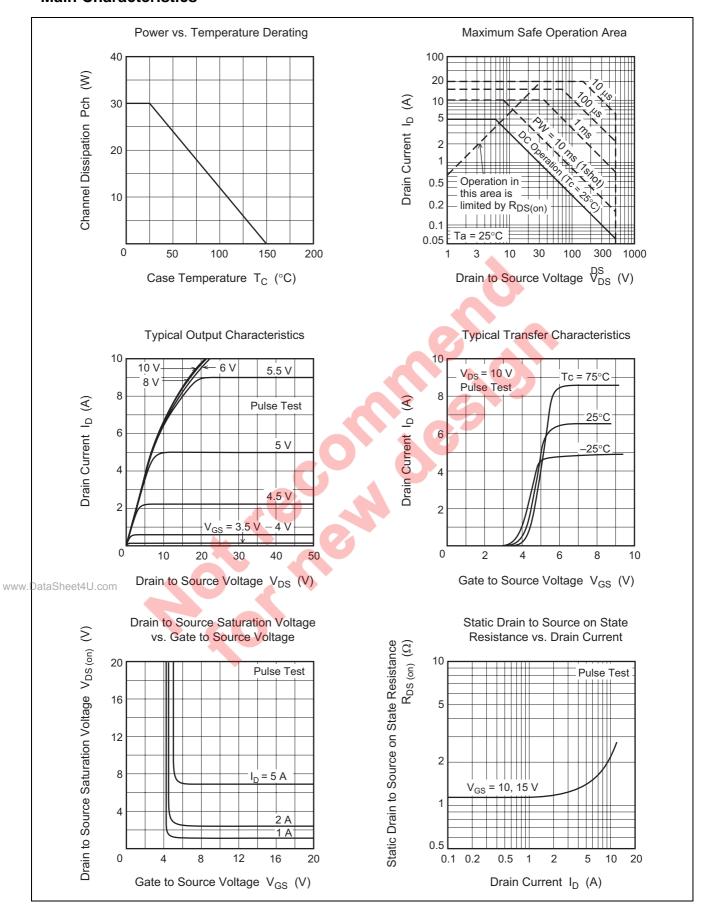
Electrical Characteristics

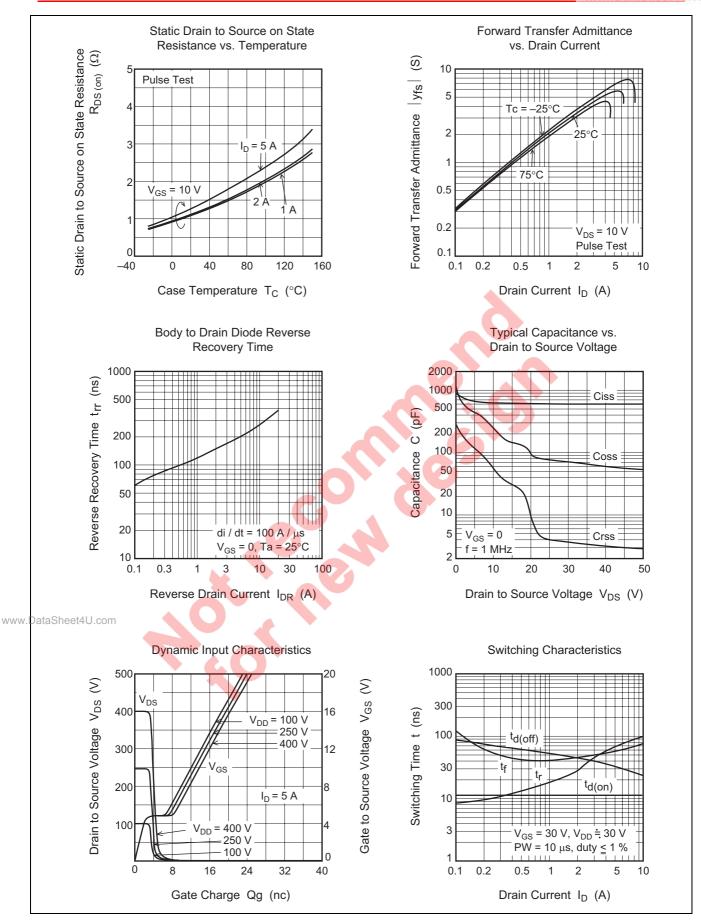
 $(Ta = 25^{\circ}C)$

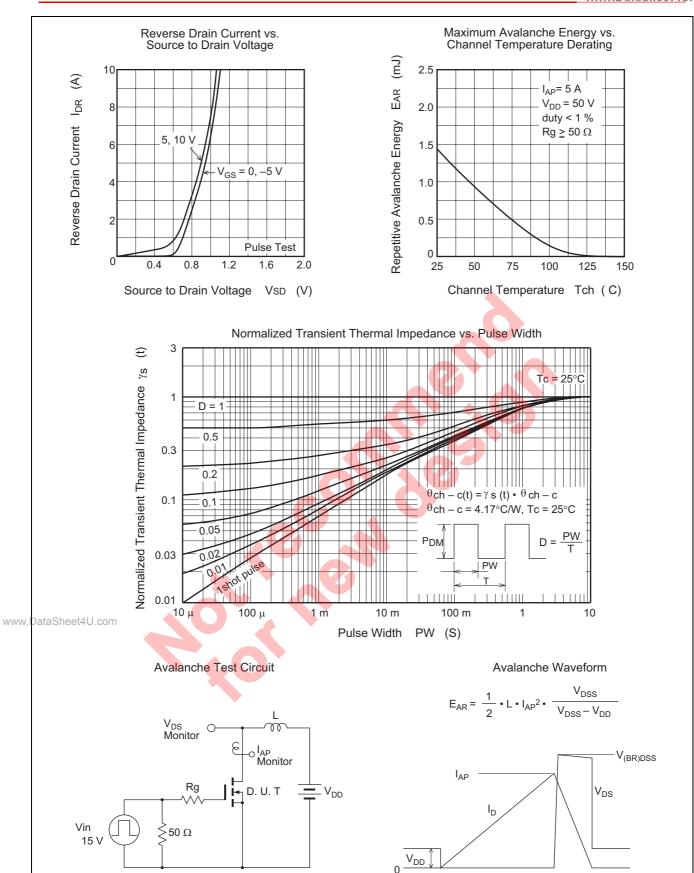
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	500		_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30		_	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$	
Gate to source leak current	I_{GSS}			±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}	1	+	10	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	2.5	Y ->	3.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{*4}$	
Static drain to source on state resistance	R _{DS(on)}	5	1.2	1.6	Ω	$I_D = 3 \text{ A}, V_{GS} = 10 \text{ V}^{*4}$	
Forward transfer admittance	y _{fs}	2.5	4.5	_	S	$I_D = 3 \text{ A}, V_{DS} = 10 \text{ V}^{*4}$	
Input capacitance	Ciss	_	630	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$	
Output capacitance	Coss	-	250	_	pF	f = 1MHz	
Reverse transfer capacitance	Crss	7	55	_	pF		
Total gate charge	Qg	-	13.5	_	nc	V _{DD} = 400 V, V _{GS} = 10 V, I _D = 5 A	
Gate to source charge	Qgs	_	3.5	_	nc		
Gate to drain charge	Qgd	_	5.0	_	nc		
Turn-on delay time	t _{d(on)}		11		ns	$V_{GS} = 10 \text{ V}, I_D = 3 \text{ A},$	
Rise time	t _r	_	45	_	ns	R _L = 10 Ω	
Turn-off delay time	t _{d(off)}	_	40	_	ns		
Fall time	t _f		50		ns		
Body to drain diode forward voltage	V_{DF}		0.95		V	$I_D = 5 A, V_{GS} = 0$	
Body to drain diode reverse recovery time	t _{rr}	_	200	_	ns	$I_F = 5 \text{ A}, V_{GS} = 0$ diF/ dt = 100 A/ μ s	

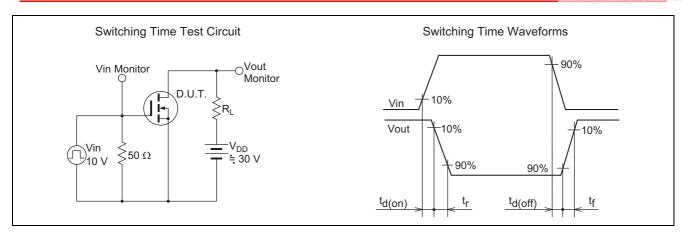
Note: 4. Pulse test

Main Characteristics



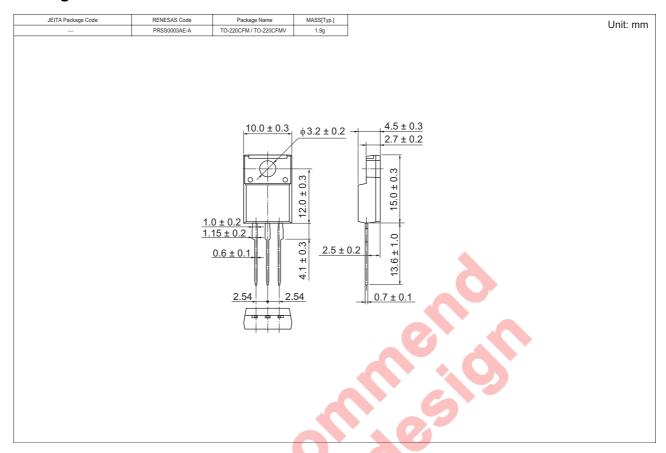








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2725-E	600 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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